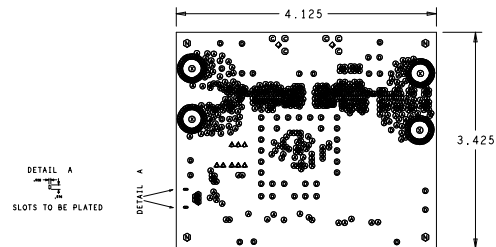


NOTE: All VIAS to be TENTED. NO exposed copper pads on any VIAS top or bottom Except VIAS in SMT pads.



#### NOTES:

1. THIS IS A 4 LAYER BOARD WITH COMPONENTS ON BOTH SIDES.
2. PRINTED CIRCUIT BOARD SHALL BE 2 OUNCE COPPER. BOARD MATERIAL TO BE EXPOXY BASED FR-4.
3. SMOBC SOLDERMASK BOTH SIDES USING RED RESIST. IAW IPC-SM-840
4. SILKSCREEN BOTH SIDE(S) USING WHITE NON CONDUCTIVE EPOXY BASED INK. TRIM ALL SILKSCREEN 4mils FROM BARE COPPER
5. MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE. ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS DIRECTIVE 20002/95/EC LAMINATE AND RESIN MATERIAL PARAMETERS  
 Tg > 170 C  
 Td > 294 C
6. ELECTROLESS NICKEL GOLD OR IMMERSION GOLD BOARD FINISH.
7. MINIMUM TRACE WIDTH 8 MILS/ SPACE 6 MILS

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	10.0	PLATED	660
•	28.0	PLATED	5
•	37.0	PLATED	6
•	41.0	PLATED	8
•	43.0	PLATED	51
•	93.0	PLATED	2
•	155.0	PLATED	4
•	128.0	NON-PLATED	4
-	76.0x28.0	PLATED	2

Drawn By: MARGARET SAVIEO	Date Drawn: 09-19-16	Engineer: Xunwei Yu
Released By:	Date Released:	ISL95338EVAL1Z Fabrication Drawing
Updated By:	Date Updated:	
		DATE IS N/A
		REV. B
FILENAME: ISL95338EVAL1ZB		SHEET 1 of 1